

YETDA INDUSTRY LTD.

Technical Data Sheet

MODEL NO: Q110YG4-X190

1206 Package 1.6*0.6mm Chip LEDs

Features :

•Package in 8mm tape on 7" diameter reel

•Compatible with automatic placement equipment

•Compatible with reflow solder process

Applications:

Indicators

•Automotive : backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
AlGaInP/GaAs	Green	Water Clear

Electrical/Optical Characteristics(Ta= $25^{\circ}C$)

Parameter	Test	Symbol	Value			Unit
	Condition		Min	Тур	Мах	Unit
Dominant wavelength	IF=20mA	λΟ	565	570	576	nm
Forward voltage	IF=20mA	VF	1.7	2.0	2.5	V
Luminous intensity	IF=20mA	lv	25	35	63	mcd
Viewing angle at 50% Iv	IF=10mA	2 <i>0</i> 1/2		140		Deg
Reverse current	Vr=5V	lr			10	μA

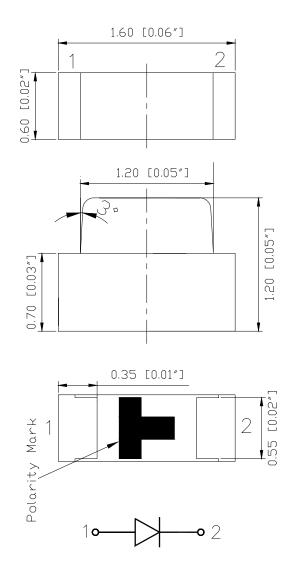
Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol Value		Unit
Power dissipation	Pd	75	mW
Forward current	lf	30	mA
Reverse voltage	Vr	5	V
Operating temperature range	Тор	-40 ~+80	°C
Storage temperature range	Tstg	-40 ~+85	°C
Peak pulsing current (1/8 duty f=1kHz)	IFP	125	mA



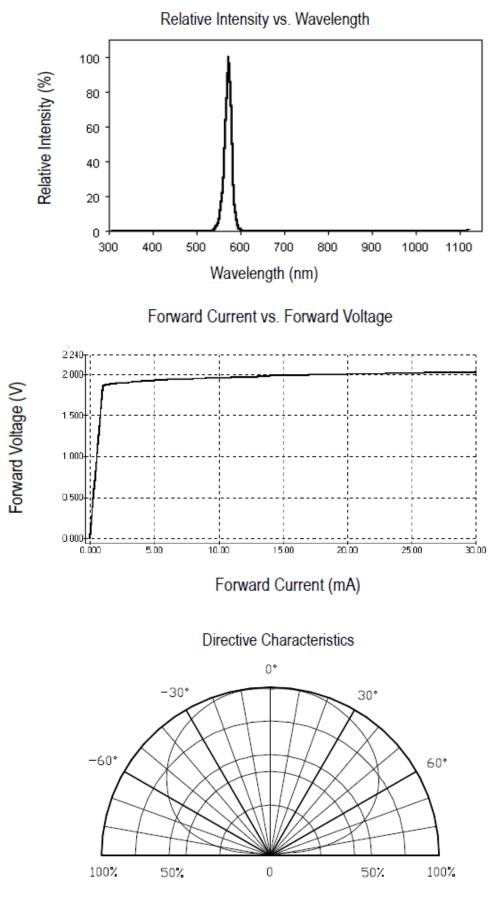
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PACKAGING DIMENSIONS (mm):





Optical Characteristic Curves





Precautions For Use :

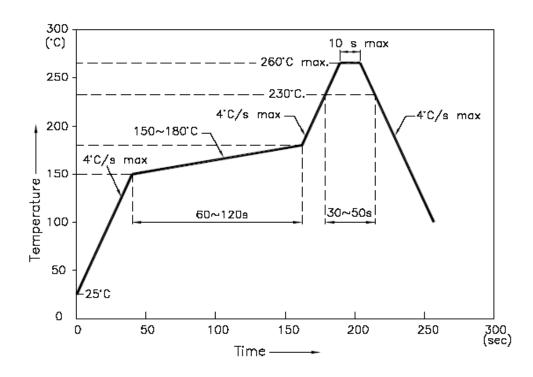
Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

1. The operation of temperature and R.H. are $: 5^{\circ}$ C $\sim 30^{\circ}$ C, 60° R.H. Max.

- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}C \pm 5^{\circ}C$ for 15 hrs.
- Reflow Temp/Time



NOTES:

- 1. We recommend the reflow temperature $245^{\circ}C(\pm 5^{\circ}C)$.the maximum soldering temperature should be limited to $260^{\circ}C$.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.



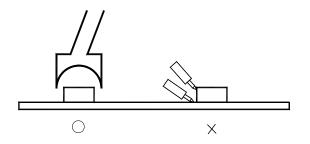
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■Soldering iron

Basic spec is ≤ 5 sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C .

Rework

- 1. Customer must finish rework within 5 sec under 260° C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow solder etc.